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Semiconductor devices –

Part 16-3: Microwave integrated circuits – Frequency converters

Dispositifs à semiconducteurs –

*Partie 16-3:
Circuits intégrés hyperfréquences –
Convertisseurs de fréquence*

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

Part 16-3: Microwave integrated circuits – Frequency converters

FOREWORD

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International Standard IEC 60747-16-3 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47E/212/FDIS	47E/219/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2008. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

SEMICONDUCTOR DEVICES –

Part 16-3: Microwave integrated circuits – Frequency converters

1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave frequency converters.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60617-12, *Graphical symbols for diagrams – Part 12: Binary logic elements*

IEC 60617-13, *Graphical symbols for diagrams – Part 13: Analogue elements*

IEC 60747-1:1983, *Semiconductor devices – Discrete devices and integrated circuits – Part 1: General*

IEC 60748-2:1997, *Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits*

IEC 60748-3, *Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits*

IEC 60748-4, *Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits*